

## AMENDMENTS TO THE CLAIMS

Upon entry of the present amendment, the status of the claims will be as is shown below.  
This listing of claims will replace all prior versions, and listings, of claims in the application.

### Listing of Claims:

1. (Currently Amended) An input signal processing device, comprising:

an input signal terminal that receives an input signal;

a connection inductance element connected to said input signal terminal at one end thereof;

a connection capacitance element connected to said input signal terminal at one end thereof;

a first grounding switching ~~means~~ unit that selectively grounds an other end of said connection inductance element; and

a second grounding switching ~~means~~ unit that selectively grounds an other end of said connection capacitance element,

wherein the other end of said connection inductance element is not connected to the other end of said connection capacitance element.

2. (Original) The input signal processing device according to claim 1, further comprising:

a grounding capacitance element that is connected to the other end of said connection inductance element, and is grounded; and

a grounding inductance element that is connected to the other end of said connection capacitance element, and is grounded.

3. (Currently Amended) The input signal processing device according to claim 1, wherein at least one of said first grounding switching ~~means~~ unit and said second grounding switching ~~means~~ unit is a semiconductor switch or an MEMS switch.

4. (Currently Amended) A high-frequency component acquisition method that uses the input signal processing device according to claim 1 to acquire a high-frequency component from the input signal, comprising:

~~a first intermediate portion grounding step of using said first grounding switching means~~  
unit to ground the other end of said connection inductance element; and

~~a second intermediate portion signal acquiring step of acquiring a signal output from the~~  
other end of said connection capacitance element.

5. (Currently Amended) A low-frequency component acquisition method that uses the input signal processing device according to claim 1 to acquire a low-frequency component from said input signal, comprising:

~~a second intermediate portion grounding step of using said second grounding switching~~  
~~means~~ unit to ground the other end of said connection capacitance element; and

~~a first intermediate portion signal acquiring step of acquiring a signal output from the~~  
other end of said connection inductance element.

6. (Currently Amended) The input signal processing device according to claim 2, wherein at least one of said first grounding switching ~~means~~ unit and said second grounding switching ~~means~~ unit is a semiconductor switch or an MEMS switch.

7. (Currently Amended) A high-frequency component acquisition method that uses the input signal processing device according to claim 2 to acquire a high-frequency component from the input signal, comprising:

~~a first intermediate portion grounding step of using said first grounding switching means~~  
unit to ground the other end of said connection inductance element; and

~~a second intermediate portion signal acquiring step of acquiring a signal output from the~~  
other end of said connection capacitance element.

8. (Currently Amended) A high-frequency component acquisition method that uses the input signal processing device according to claim 3 to acquire a high-frequency component from the input signal, comprising:

~~a first intermediate portion grounding step of using said first grounding switching means~~  
unit to ground the other end of said connection inductance element; and

~~a second intermediate portion signal acquiring step of acquiring a signal output from the~~  
other end of said connection capacitance element.

9. (Currently Amended) A high-frequency component acquisition method that uses the input signal processing device according to claim 6 to acquire a high-frequency component from the input signal, comprising:

~~a first intermediate portion grounding step of using said first grounding switching means~~  
unit to ground the other end of said connection inductance element; and

~~a second intermediate portion signal acquiring step of acquiring a signal output from the~~  
other end of said connection capacitance element.

10. (Currently Amended) A low-frequency component acquisition method that uses the input signal processing device according to claim 2 to acquire a low-frequency component from said input signal, comprising:

~~a second intermediate portion grounding step of using said second grounding switching~~  
means unit to ground the other end of said connection capacitance element; and

~~a first intermediate portion signal acquiring step of acquiring a signal output from the~~  
other end of said connection inductance element.

11. (Currently Amended) A low-frequency component acquisition method that uses the input signal processing device according to claim 3 to acquire a low-frequency component from said input signal, comprising:

~~a second intermediate portion grounding step of using said second grounding switching~~  
means unit to ground the other end of said connection capacitance element; and

~~a first intermediate portion signal acquiring step of acquiring a signal output from the~~  
other end of said connection inductance element.

12. (Currently Amended) A low-frequency component acquisition method that uses the input signal processing device according to claim 6 to acquire a low-frequency component from said input signal, comprising:

~~a second intermediate portion grounding step of~~ using said second grounding switching means unit to ground the other end of said connection capacitance element; and

~~a first intermediate portion signal acquiring step of~~ acquiring a signal output from the other end of said connection inductance element.

13. (Currently Amended) An input signal processing device, comprising:

an input signal terminal that receives an input signal;

a connection inductance element connected to said input signal terminal at one end thereof;

a connection capacitance element connected to said input signal terminal at one end thereof;

a first grounding switch that selectively grounds an other end of said connection inductance element and

a second grounding switch that selectively grounds an other end of said connection capacitance element,

wherein the other end of said connection inductance element is not connected to the other end of said connection capacitance element.

14. (Previously Presented) The input signal processing device according to claim 13, further comprising:

a grounding capacitance element connected to the other end of said connection inductance element, and is grounded; and

a grounding inductance element connected to the other end of said connection capacitance element, and is grounded.

15. (Previously Presented) The input signal processing device according to claim 13, wherein at least one of said first grounding switch and said second grounding switch comprises one of a semiconductor switch and a MEMS switch.

16. (Previously Presented) A high-frequency component acquisition method that uses the input signal processing device according to claim 13 to acquire a high-frequency component from the input signal, comprising:

using said first grounding switch to selectively ground an other end of the connection inductance element; and

acquiring a signal output from the other end of the connection capacitance element.

17. (Previously Presented) A low-frequency component acquisition method that uses the input signal processing device according to claim 13 to acquire a low-frequency component from said input signal, comprising:

using said second grounding switch to selectively ground an other end of the connection capacitance element; and

acquiring a signal output from the other end of the connection inductance element.